Selective Soldering System by Nordson ELECTRONICS SOLUTIONS



The SELECT Synchro is a multi-station selective soldering system designed for high-volume applications with maximum throughput. With its highly flexible configuration, the SELECT Synchro allows soldering of printed circuit boards as large as 460 x 2500 mm.

Versatility. Customers can choose between three, four, or five solder pots and different variants of the additional options to meet a broad range of selective soldering requirements. The Select Synchro configuration with drop-jet fluxer and five solder pots allows for using up to five different solder nozzles or alloys in the same process. The Synchro is capable of processing up to 7 boards at the same time.

Value. With a reputation for innovation, comprehensive process solutions from Nordson SELECT ensure a maximum return on investment and low cost of ownership. From initial process development through full-scale production, you are supported by our experienced worldwide engineering, applications development and technical service network.

Features and Benefits

- FAST; Increased throughput due to elimination of wasted convey time 20% to 30% on most applications, higher savings if the convey time is large compared to the soldering time of one station
- SMART; Automatically balancing the whole process which significantly increases machine throughput and broadens soldering flexibility at its best
- SPACE-EFFICIENT; Over 50% reduction in size due to a large reduction of pot and fluxer motion in the conveyor direction. Machine dimensions 2.5m x 1.5m for 2, 3, 4 and 5 pot configurations
- HIGH THROUGHPUT; Board dimensions 2,500mm+ X 460mm. Since the board travels at a constant speed on the conveyor, theoretically the conveyor direction dimension is limitless
- FLEXIBLE; Allows use of different alloys and different nozzles or one fixed nozzle layout for all of your products







Selective Soldering System by Nordson ELECTRONICS SOLUTIONS

Features

The Select Synchro is a fully configured SMEMA compatible selective soldering platform and is a reliable and cost-effective solution for many demanding through-hole and SMT mixed-technology soldering applications including:

- Double-sided TH/SMT assemblies
- TH selective and mini-wave soldering
- Multiple solder alloy soldering without changing solder pot



Standard Features

Seven-zone operation with independent zones for concurrent fluxing and preheating plus 5 single selective soldering station SMEMA conveyor with positive PCB location Automatic conveyor width adjustment MicroDrop drop-jet fluxer Flux level sensing system Full surface bottom-side infrared preheating

All titanium solder pot and pump assembly

Quick change magnetically coupled solder nozzle

PhotoScan editor and machine control software

- Easy "point-and-click" programming
- Remote machine control
- Remote machine maintenance
- Network and FIS capability TFT monitor

Optional Features

Fully-automated fiducial alignment and board mapping In-process, closed-loop flux verification system for drop-jet control

- Full surface topside infrared preheating
- Closed-loop pyrometer control
- Board warpage sensing system
- Process viewing camera and second monitor
- Automatic solder wire feeding system
- Automatic solder level sensing system
- Wave height control sensing system
- Automatic solder nozzle cleaning system
- AOI solder joint inspection system
- Data logging system with traceability of all process parameters, barcode reader
- Automatic wave height monitoring
- MES capability



Specifications

Motion System

Z accuracy: ±100 μm (0.004 in.) Z repeatability (1): ±50 μm (0.002 in.), 3 sigma Z velocity: 0.05 m/s peak (2 in./s) ±100 μm (0.004 in.) X-Y accuracy: X-Y repeatability (1): ±50 μm (0.002 in.), 3 sigma X-Y velocity: 0.2 m/s peak (8 in./s)

Computer

PC with Windows® operating system

Software

PhotoScan "point-and-click" programming editor and machine control software

Approx. 12.0 kg (26.4 lbs.)

Approx. 22.4 kg (49.2 lbs.)

Approx. 19.7 kg (43.3 lbs.)

320°C

Solder Pot Capacity and Weight

Capacity (2): Total weight of tin-lead solder together with solder pot and pump assembly ⁽²⁾:

Total weight of lead-free solder together with solder pot and pump assembly ⁽²⁾:

Max. temperature:

Solderable Area (X-Y)

Max. 460 x 2500 mm Min. 50 x 100 mm

Preheating

Selectable topside preheating from 1.5 kW to 24.0 kW Selectable bottom preheating from 1.5 kW to 9.0 kW

Board Handling Capability

Max. board size: 460 x 2500 mm Min. board size: 50 x 100 mm

Conveyor

Min./Max. board/carrier thickness: Max. overboard clearance: Max. underboard clearance: Edge clearance (5): Transport height (6):

Load capacity ⁽⁷⁾: Operation modes: 0.5m to 5 mm 120 mm 80 mm 3 mm (0.12 in.), edge conveyor including on-rail clamps Conforms to SMEMA standard for conveyor height; height adjustable from 940-965 mm from floor to bottom of board 5.0 kg/PCB complete 30 kg

Automatic (SMEMA), manual or pass-through

Facilities Requirements

System footprint: 2500 x 1500 mm Compressed air: 6 bar min., 8 bar max. Power (mains) (8): 400/480VAC, 50-60 Hz, three phase, 50 kW, 72 A 99.99% (4.0) pure, 4-6 bar, 1.3 m³/hour (single pot), 6.5 m³/ hour (5 solder pots) Ventilation: Rear 300 m³/hour, two 100 mm dia. Ducts System weight (9, 10): 1800 kg

Explanatory Notes

SMEMA, CE

Standards Compliance

Nitrogen:

- 1. Repeatability is measured at full rated system speed.
- 2. Solder capacity and total weight of solder pot and pump assembly varies depending on solder alloy.
- 3. Board size is reduced when operating in parallel or double modes
- 4. Contact factory regarding smaller or larger boards/carriers.
- 5. Edge conveyor conforms to SMEMA standards.
- 900 mm (35.4 in.) non-SMEMA conveyor height available upon 6. request.
- 7. Total weight of all parts on conveyor at any one time. Contact factory regarding requirements for greater load capacity.
- 8. Electrical power varies depending on configuration.
- 9. System weight varies depending on configuration.
- 10. Configuration dependent. Other configurations may be available. Contact Nordson SELECT

Windows is a registered trademark of Microsoft Corporation in the United States and other countries.

Additional options may be available: contact Nordson SELECT for further information.



Dimensions are in millimeters



Top View (mm)



Front View (mm)







The SCCE (Soldering Competence Center Europe) is a division of smartTec and your partner for all aspects of soldering. An extensive training and seminar program as well as process know-how, development and support are emphasized in the SCCE.

The SCCE will be pleased to advise you with your questions:

info@smarttec.de

+49 6106 6670-0

smarttec.de

